



OL-IP3319CX6

Wafer level chip-size package; 6 bumps (2 x 3); 0.4 mm pitch;
0.95 mm x 1.34 mm x 0.6 mm body

7 June 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	11-6-2013
Manufacturer package code	WLCSP6

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.9	-	0.95	1	mm
E	package width	1.29	-	1.34	1.39	mm
A	seated height	0.54	-	0.57	0.6	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	6	-	

2. Package outline

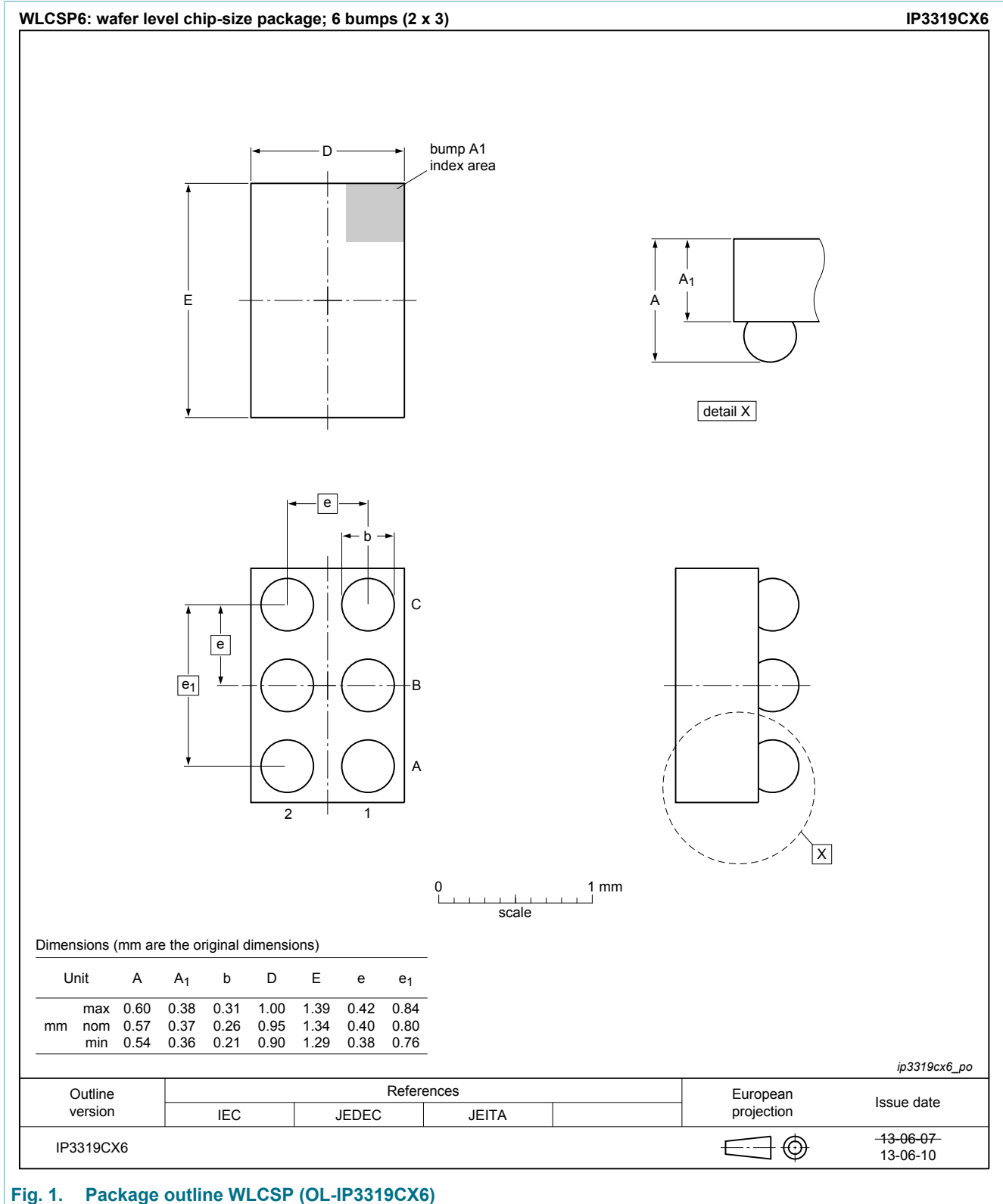


Fig. 1. Package outline WLCSP (OL-IP3319CX6)

3. Legal information

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